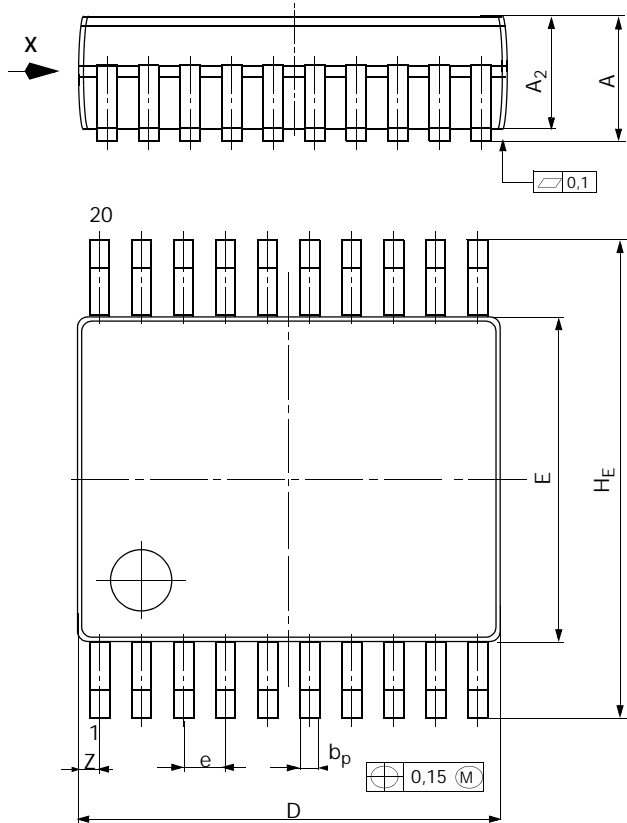
	Package SSOP20 (5,3 mm)	MDS 757
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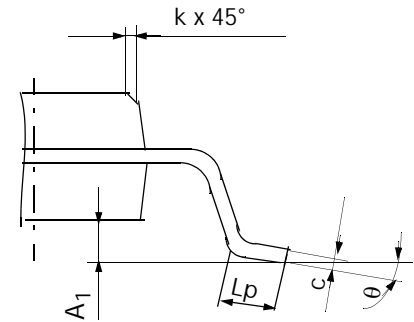
Dimensions in millimetres

Supersedes
Edition 11.99

Based on JEDEC JEP95: MO-150

1 Dimensions

View X



Dimensions of Sub-Group B1	
A_{max}	1,99
b_{Pmin}	0,25
b_{Pmax}	0,38
e_{nom}	0,65
H_{Emin}	7,65
H_{Emax}	7,90
L_{Pmin}	0,63
Z_{max}	0,74

Dimensions of Sub-Group C1	
A_{min}	1,73
A_{1min}	0,05
A_{1max}	0,21
A_{2min}	1,68
A_{2max}	1,78
c_{min}	0,09
c_{max}	0,20
D_{min}^*	7,07
D_{max}^*	7,33
E_{min}^*	5,20
E_{max}^*	5,38
k_{min}	0,25
θ_{min}	0°
θ_{max}	10°

- 2 **Weight** $\leq 0,3$ g
- 3 **Package Body Material** Low Stress Epoxy
- 4 **Lead Material** FeNi-Alloy or Cu-Alloy
- 5 **Lead Finish** solder plating
- 6 **Lead Form** Z-bends

* without mold-flash

Zentrum Mikroelektronik Dresden AG		
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